



BSI Standards Publication

Integrated circuits – Three dimensional integrated circuits

Part 2: Alignment of stacked dies having fine pitch interconnect

National foreword

This British Standard is the UK implementation of IEC 63011-2:2018.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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Amendments/corrigenda issued since publication

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